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11. Reserve

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5. PMU TPS65910

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3. POWER TREE

2. system block

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25. Hi6756 RF Interface

26. MCP (8x9 package size)

27. Hi6756 Function IO

28. Hi6756 Power

29. Hi6451 PMU

30~37. Reserve

38. TCXO+ANT

39. HI6360

40. WCDMA TX

41. GSM PA+Switch

42. WCDMA Duplexer

43. DIVERSITY

44. Reserve

*45. SIM¿¨½Ó¿Ú¼°USBµ÷ÊÔ¿ª¹Ø

*46. Test Points/JTAG/Shields

*47. Shielding Class

The type and specification of the components refer to the BOM.
2. System block

- Charger: BQ24161
- PMU: TPS659102
- Buck: TPS62366AYZHR
- Buck: TPS62065DSGR
- DDR3: 256MBX4
- F Camera: 3M
- B Camera: 0.3M
- TP

- PWM/GPIO
- LCD DRV/EL
  - DRV: MPS1530
  - BL: RT9293
- 1024X600
- RGB888
- RGB TO LVDS/LVDS

- AP: RK3168
- Modem: HI6360, HI6451
- Modem RF
- Modem BB: HI6756
- Modem PMU
- UART
- GPS: BCM47511
- SDIO: WF/BT: BCM4330
- SPI
- Codec: AIC3262
- MIC
- Speaker
- Receiver

The type and specification of the components refer to the BOM.

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3. POWER TREE

AP PMU TPS659102

BUCK1 VDD_LOG_AP RK3168 GPU

BUCK2 VCCIO_33_AP EMMC, TF, Codec, Motor

BUCK3 VCCIO CAM

LD01 VCCIO_CAM CAM

LD02 VDD_1V2 HSIC

LD01 AP PMU

LD02

LD03 VCC28_CIF

LD04 VCC_18

LD05 VCCA_33

LD06 VCC_1V0

LD07

LD08

TPS62065 VDD_ARM_AP RK3168 CPU

VDD_ARM_AP

VCC_AP_DDR3 DDR3 X 4

RT9297GW VREG_5V Codec PA, USB OTG power

VREG_5V

TPS62366 VDD_ARM_AP

VPH_PWR_MDM

HI6451 modem V3R2

VPH_PWR_MDM

The type and specification of the components refer to the BOM
4. DC/CHARGER

BQ24161 Charger

Note: Slave address 0x68

USB VBUS power control

Fuel Gauge

battery Connector

The type and specification of the components refer to the BOM
The type and specification of the components refer to the BOM.
7. DDR3

The type and specification of the components refer to the BOM.
The type and specification of the components refer to the BOM.
The type and specification of the components refer to the BOM.
The type and specification of the components refer to the BOM.
11.CPU_GPIO

The type and specification of the components refer to the BOM
The type and specification of the components refer to the BOM.
14. Reserve

The type and specification of the components refer to the BOM

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ECA NO: DATE

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SH1S7701UM 03022FVG_SCHZH

VER PART_NUMBER SHEET 14 OF 47
A 03022FVG HUAWEI TECH CO., LTD.
15. INTERFACE

RK3126 TF card part

TF/card part

The type and specification of the components refer to the BOM
16. RESET AND USB_DET

The type and specification of the components refer to the BOM.

Power button

R1612 80.6K
PWR_HOLD_AP

USB_INT

R1600 4.7K
VBS0

MMBT2369ALT1G
Q1600

C1604 100P
10K

R1609

D1603 BAV70E6327
PWRHOLD

R1604 150K
PWRON

VSYS

R1603 **47K

R1610 47K

D1600

R1607 47K

A03022FVG

SH1S7701UM

03022FVG_SCHZH

CHENGLINHUI 00144651

MIIKE LIU 81004891

VER PART_NUMBER SHEET 16 OF 47
A 03022FVG HUAWEI TECH CO., LTD.
The type and specification of the components refer to the BOM
19. G_SENSOR AND COMPASS

**Accelerometer**

- **Note:** Slave address
  - LIS3DHTR -- ST: 0011000b/0x18
  - MMA8452QR1 -- FREESCALE: 0011100b/0x1C

**Compass**

- **Note:** Slave address
  - [AKM8963]: 0CH
  - [YMH YAS533]: 2EH

The type and specification of the components refer to the BOM.
The type and specification of the components refer to the BOM.
21. WIFI RF

The type and specification of the components refer to the BOM.
The type and specification of the components refer to the BOM.
23. TEST Points

For debug

For Manufacture

The type and specification of the components refer to the BOM
24. Power of LCD

The type and specification of the components refer to the BOM.

- The frequency of the components is ±490Hz.
- The input voltage is ±210Hz.

The diagram shows the connections between various components, including power regulation, biasing, and other related functions. The components are labeled with their types and values, such as capacitors, resistors, and other electronic parts.

The schematic includes connections to LCD connectors and various voltage levels, indicating the setup for a power management system for a liquid crystal display (LCD).
25. Hi6756 RF Interface

The type and specification of the components refer to the BOM.
27. Hi6756 Function IO

The type and specification of the components refer to the BOM.
28. Hi6756 Power

The type and specification of the components refer to the BOM.
29. Hi6451 PMU

The type and specification of the components refer to the BOM.
30. Reserve

The type and specification of the components refer to the BOM

SH1S7701UM 03022FVG_SCHZH
MIKE LIU 81004891
CHENGLINHUI 00144651

VER PART_NUMBER SHEET 30 OF 47
A 03022FVG HUAWEI TECH CO., LTD
31. Reserve

The type and specification of the components refer to the BOM

ECA NO: 03022FVG_SCHZH
DATE: 2013-03-11

DESIGNED: MIKE LIU 81004891

REVISED: CHENGLINHUI 00144651

VER: A
PART_NUMBER: 03022FVG
SHEET 31 OF 47

HUAWEI TECH CO., LTD.
32. Reserve

The type and specification of the components refer to the BOM.
The type and specification of the components refer to the BOM.

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**DESIGNED**

MIEK LIU 81004891

**REVIEWED**

CHENGLINHUI 00144651

**VER**

A

**PART_NUMBER**

03022FVG

**SHEET**

33 OF 47

**HUAWEI TECH CO., LTD.**
The type and specification of the components refer to the BOM.
The type and specification of the components refer to the BOM

ECA NO  2013-03-11
ECA NO  

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REVIEVED CHENGLINHUI 00144651  

VER  PART_NUMBER  SHEET 35 OF 47

A  03022FVG  HUAWEI TECH CO., LTD

SH1S7701UM  03022FVG_SCHZH

35. Reserve
36. Reserve

The type and specification of the components refer to the BOM.
37. Reserve

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The type and specification of the components refer to the BOM.
The type and specification of the components refer to the BOM.
40. WCDMA TX

W_B1

W_B2

W_B5/B8

The type and specification of the components refer to the BOM
41. GSM PA+Switch

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The type and specification of the components refer to the BOM.
42. WCDMA Duplexer

The type and specification of the components refer to the BOM
43. DIVERSITY

The type and specification of the components refer to the BOM.

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<th>Ant1 Di Sel0</th>
<th>Ant1 Di Sel1</th>
<th>Ant1 Di Sel2</th>
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<tbody>
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</tr>
<tr>
<td>RF2</td>
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<tr>
<td>RF3</td>
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</tbody>
</table>
44. Reserve

The type and specification of the components refer to the BOM
The type and specification of the components refer to the BOM.
46. Test Points/JTAG/Shields

For debug

MODEM JTAG for debug

For Manufacture

The type and specification of the components refer to the BOM.